

SCES090I-OCTOBER 1996-REVISED SEPTEMBER 2004

DGG. DGV. OR DL PACKAGE

#### **FEATURES**

- Member of the Texas Instruments Widebus™ Family
- **EPIC™** (Enhanced-Performance Implanted **CMOS) Submicron Process**
- **Designed to Comply With JEDEC 168-Pin and** 200-Pin SDRAM Buffered DIMM Specification
- ESD Protection Exceeds 2000 V Per MIL-STD-883. Method 3015: Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- **Package Options Include Plastic Shrink** Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

#### DESCRIPTION

This 16-bit universal bus driver is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

Data flow from A to Y is controlled by the output-enable (OE) input. The device operates in the transparent mode when the latch-enable (LE) input is low. When  $\overline{\text{LE}}$  is high, the A data is latched if the clock (CLK) input is held at a high or low logic level. If LE is high, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

JGG, L			P VII	(TOP VIEW)											
	1	-													
ŌĒ	Γ	1	U	48	þ	CLK									
Y1	Γ	2		47		A1									
Y2		3		46		A2									
GND	Γ	4		45		GND									
Y3		5		44		A3									
Y4		6		43		A4									
$V_{CC}$	Γ	7		42		V <sub>CC</sub>									
Y5		8				A5									
Y6		9				A6									
GND		10		39		GND									
Y7		11				A7									
Y8		12		37		A8									
Y9		13				A9									
Y10		14			_	A10									
GND		15			_	GND									
Y11		16		33		A11									
Y12		17		32		A12									
$V_{CC}$	Ū	18				V <sub>CC</sub>									
Y13		19		30		A13									
Y14	g	20		29		A14									
GND	Ū	21		28		GND									
Y15	L	22		27		A15									
Y16	Ľ	23		26	Ľ	A16									
NC	[	24		25		LE									

NC - No internal connection

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>cc</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16334 is characterized for operation from -40°C to 85°C.

	INF	PUTS		OUTPUT
ŌĒ	LE	CLK	Α	Y
Н	Х	Х	Х	Z
L	L	Х	L	L
L	L	х	Н	н
L	Н	$\uparrow$	L	L
L	Н	$\uparrow$	Н	н
L	Н	L or H	Х	Y <sub>0</sub> <sup>(1)</sup>

#### **FUNCTION TABLE**

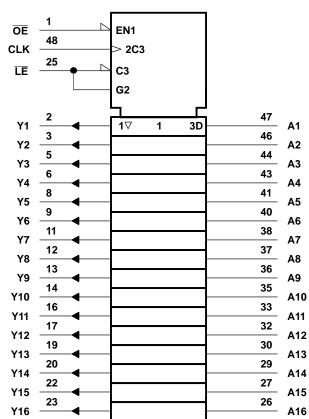
Output level before the indicated steady-state input conditions were (1) established



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#### LOGIC SYMBOL<sup>(1)</sup>

(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# LOGIC DIAGRAM (POSITIVE LOGIC) OE 1 CLK 48 LE 25 A1 47 A1 CLK 2 Y1

To 15 Other Channels



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## **ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	4.6	V
VI	Input voltage range <sup>(2)</sup>		-0.5	4.6	V
Vo	Output voltage range <sup>(2)(3)</sup>		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
I <sub>O</sub>	Continuous output current			±50	mA
	Continuous current through each V <sub>CC</sub> or GN	ID		±100	mA
		DGG package		89	
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DGV package		93	°C/W
		DL package		94	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This value is limited to 4.6 V maximum.

(4) The package thermal impedance is calculated in accordance with JESD 51.

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## **RECOMMENDED OPERATING CONDITIONS**<sup>(1)</sup>

			MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage		1.65	3.6	V	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65  imes V_{CC}$			
VIH	High-level input voltage	$V_{CC}$ = 2.3 V to 2.7 V	1.7		V	
		$V_{CC} = 2.7 V \text{ to } 3.6 V$	2			
		V <sub>CC</sub> = 1.65 V to 1.95 V	(	$0.35 \times V_{CC}$		
VIL	Low-level input voltage	$V_{CC}$ = 2.3 V to 2.7 V		0.7	V	
		$V_{CC} = 2.7 V \text{ to } 3.6 V$		0.8		
VI	Input voltage		0	V <sub>CC</sub>	V	
Vo	Output voltage		0	V <sub>CC</sub>	V	
		V <sub>CC</sub> = 1.65 V		-4		
		V <sub>CC</sub> = 2.3 V		-12	mA	
I <sub>ОН</sub>	High-level output current	V <sub>CC</sub> = 2.7 V		-12		
		$V_{CC} = 3 V$		-24		
		V <sub>CC</sub> = 1.65 V		4		
	Low lovel output ourrent	V <sub>CC</sub> = 2.3 V		12	mA	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		12		
		$V_{CC} = 3 V$		24		
$\Delta t / \Delta v$	Input transition rise or fall rate	· · · · · ·		10	ns/V	
T <sub>A</sub>	Operating free-air temperature		-40	85	°C	

(1) All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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#### **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

P/	ARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN	<b>TYP</b> <sup>(1)</sup>	MAX	UNIT				
		I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2							
		I <sub>OH</sub> = -4 mA	1.65 V	1.2							
		I <sub>OH</sub> = -6 mA	2.3 V	2							
V <sub>OH</sub>			2.3 V	1.7			V				
		I <sub>OH</sub> = -12 mA	2.7 V	2.2							
			3 V	2.4							
		I <sub>OH</sub> = -24 mA	3 V	2							
		I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.2					
		I <sub>OL</sub> = 4 mA	1.65 V			0.45					
		I <sub>OL</sub> = 6 mA	2.3 V			0.4	V				
V <sub>OL</sub>	40	2.3 V		0.7							
	$I_{OL} = 12 \text{ mA}$	2.7 V			0.4						
	I <sub>OL</sub> = 24 mA	3 V			0.55						
l <sub>l</sub>		$V_{I} = V_{CC}$ or GND	3.6 V			±5	μA				
		V <sub>1</sub> = 0.58 V	1.65 V	25							
		V <sub>I</sub> = 1.07 V	1.65 V	-25							
		V <sub>1</sub> = 0.7 V	2.3 V	45							
I <sub>I(hold)</sub>		V <sub>1</sub> = 1.7 V	2.3 V	-45			μA				
. ,		V <sub>1</sub> = 0.8 V	3 V	75							
		$V_1 = 2 V$	3 V	-75							
		$V_1 = 0$ to 3.6 V <sup>(2)</sup>	3.6 V			±500					
I <sub>OZ</sub>		$V_{O} = V_{CC}$ or GND	3.6 V			±10	μA				
I <sub>CC</sub>		$V_{I} = V_{CC}$ or GND, $I_{O} = 0$	3.6 V			40	μA				
Δl <sub>CC</sub>		One input at $V_{CC}$ - 0.6 V, Other inputs at $V_{CC}$ or GND	3 V to 3.6 V			750	μA				
	Control inputs		2.2.1		5.5		_				
Ci	Data inputs	$V_1 = V_{CC}$ or GND	3.3 V		6	pF					
Co	Outputs	$V_{O} = V_{CC}$ or GND	3.3 V		8		pF				
	1		1								

(1)

All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to (2) another.

#### TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

				V <sub>CC</sub> =	1.8 V	V <sub>CC</sub> = ± 0.	2.5 V 2 V	V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = ± 0.	3.3 V 3 V	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$f_{clock}$	f <sub>clock</sub> Clock frequency						150		150		150	MHz
t., Pulse duration	LE low				3.3		3.3		3.3		ns	
t <sub>w</sub>	Fuise duration	CLK high or low	(1)		3.3		3.3		3.3			
		Data before CLK↑				1.4		1.7		1.5		ns
t <sub>su</sub>	Setup time	Data before LE↑	CLK high	(1)		1.2		1.6		1.3		
		Data before LE	CLK low	(1)		1.4		1.5		1.2		
÷	Hold time	Data after CLK↑				0.9		0.8		0.9		ns
t <sub>h</sub>		Data after $\overline{\text{LE}}$	CLK high or low	(1)		1.2		1.1		1.1		

(1) This information was not available at the time of publication.

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## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	-	TO (OUTPUT)	V <sub>CC</sub> = 1	.8 V	V <sub>CC</sub> = 2 ± 0.2	2.5 V V	V <sub>CC</sub> = 2	.7 V	V <sub>CC</sub> = 3 ± 0.3	8.3 V V	UNIT
		(001201)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX		
f <sub>max</sub>			(1)		150		150		150		MHz	
	А			(1)	1	3.7		3.6	1.1	3.3		
t <sub>pd</sub>	LE	Y		(1)	1	4.8		5	1.3	4.4	ns	
	CLK			(1)	1	4.4		4.5	1	4.1		
t <sub>en</sub>	OE	Y		(1)	1	5.4		5.4	1.1	4.6	ns	
t <sub>dis</sub>	OE	Y		(1)	1	4.1		4.5	1.7	4.4	ns	

(1) This information was not available at the time of publication.

## **OPERATING CHARACTERISTICS**

 $T_A = 25^{\circ}C$ 

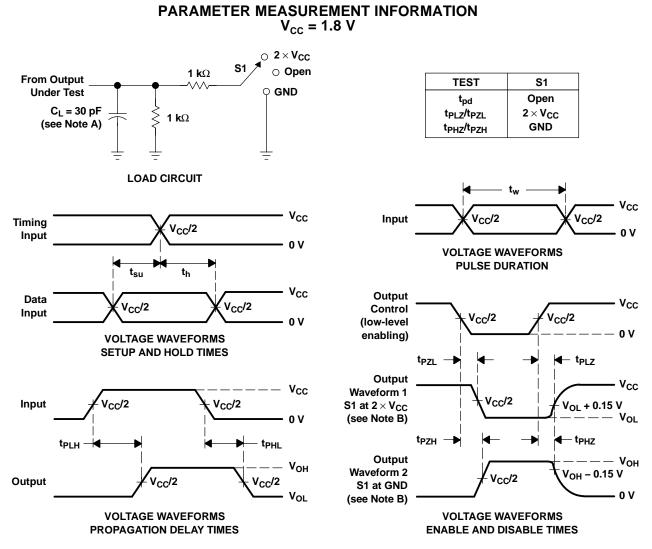
	PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	UNIT	
C	Dower dissipation expectiones	Outputs enabled	C = 0.5 = 10  MHz	(1)	32	37	pF	
Cpd	Power dissipation capacitance	Outputs disabled	$C_{L} = 0, f = 10 \text{ MHz}$	(1)	7	11	рг	

(1) This information was not available at the time of publication.

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# SN74ALVCH16334 16-BIT UNIVERSAL BUS DRIVER WITH 3-STATE OUTPUTS

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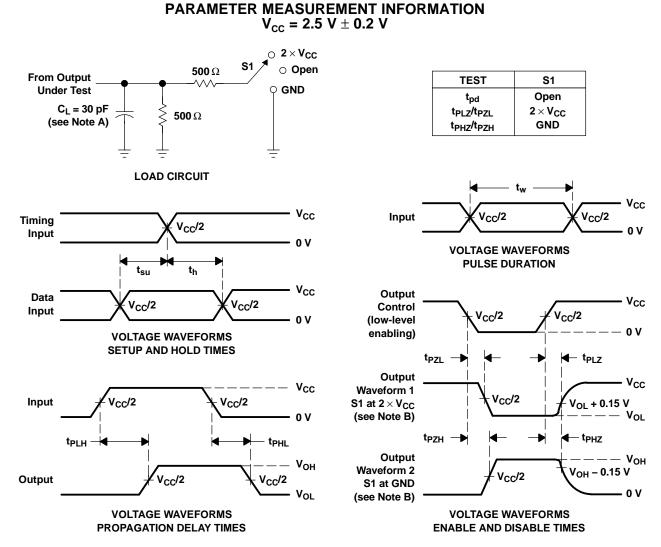
#### NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>r</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

#### Figure 1. Load Circuit and Voltage Waveforms



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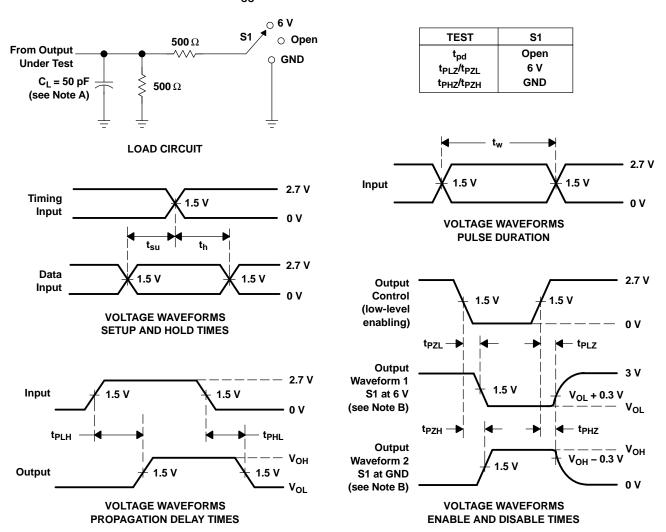
- NOTES: A. C<sub>1</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

#### Figure 2. Load Circuit and Voltage Waveforms



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#### PARAMETER MEASUREMENT INFORMATION $V_{cc}$ = 2.7 V AND 3.3 V $\pm$ 0.3 V



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns. The outputs are measured one at a time, with one transition per measurement. D.
  - E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 3. Load Circuit and Voltage Waveforms



10-Dec-2020

# PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALVCH16334DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16334	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <= 1000ppm threshold. Antimony trioxide based flame retardants must also meet the <= 1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(<sup>6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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5-Jan-2022

# TUBE



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN74ALVCH16334DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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